

WHAT IS CLAIMED IS:

1. An electronic component characterized by its structure wherein a heat conductive adhesive made by blending boron nitride powder that has a diamagnetic an-isotropic magnetic susceptibility and adhesive polymer is interposed between a heating device and a heat conductive member, and adhering with boron nitride powder oriented in the heat conductive adhesive to a fixed direction under a magnetic field atmosphere by the use of the diamagnetic an-isotropic magnetic susceptibility of the boron nitride powder.
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